



GreenMOS™

OSG65R125xF_Datasheet



Enhancement Mode N-Channel Power MOSFET

Features

- ◆ Low $R_{DS(on)}$ & FOM
- ◆ Excellent low switching loss
- ◆ Excellent stability and uniformity
- ◆ Easy to drive

Applications

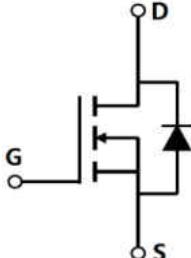
- ◆ PC power
- ◆ Server power supply
- ◆ Telecom
- ◆ Solar invertor
- ◆ Super charger for automobiles

■ General Description

OSG65R125xF use advanced GreenMOS™ technology to provide low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. This device is suitable for telecom and super charger applications.

◆ V_{DS} , min@ T_{jmax}	700 V
◆ I_D , pulse	75 A
◆ $R_{DS(ON)}$, max @ $V_{GS}=10$ V	125 mΩ
◆ Q_g	41.9 nC

■ Schematic and Package Information

SCHEMATIC DIAGRAM	PIN ASSIGNMENT-TOP VIEW		
	TO247 OSG65R125HF	TO263 OSG65R125KF	TO220F OSG65R125FF
			

■ Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

PARAMETER	SYMBOL	VALUE	UNIT
Drain source voltage	V_{DS}	650	V
Gate source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	25	A
Continuous drain current ¹⁾ , $T_C=100^\circ\text{C}$		16	
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	I_D , pulse	75	A
Power dissipation ³⁾ for TO263, TO247, $T_C=25^\circ\text{C}$	P_D	219	W
Power dissipation ³⁾ for TO220F, $T_C=25^\circ\text{C}$		34	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	730	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\dots 480$ V	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0\dots 480$ V, $I_{SD} \leq I_D$	dv/dt	15	V/ns
Operation and storage temperature	T_{stg} , T_j	-55 to 150	°C

■ Thermal Characteristics

Parameter	Symbol	Value		Unit
		TO247/TO263	TO220F	
Thermal resistance, junction-case	R _{θJC}	0.57	3.7	°C/W
Thermal resistance, junction-ambient ⁴⁾	R _{θJA}	62	62.5	°C/W

■ Electrical Characteristics at T_j=25 °C unless otherwise specified

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION
Drain-source breakdown voltage	BV _{DSS}	650			V	V _{GS} =0 V, I _D =1 mA
		700	740			V _{GS} =0 V, I _D =1 mA, T _j =150 °C
Gate threshold voltage	V _{GS(th)}	2.9		3.9	V	V _{DS} =V _{GS} , I _D =1 mA
Drain-source on-state resistance	R _{DS(ON)}		0.115	0.125	Ω	V _{GS} =10 V, I _D =12.5 A
			0.278			V _{GS} =10 V, I _D =12.5 A, T _j =150 °C
Gate-source leakage current	I _{GSS}			100	nA	V _{GS} =30 V
				-100		V _{GS} =-30 V
Drain-source leakage current	I _{DSS}			1	μA	V _{DS} =650 V, V _{GS} =0 V

■ Dynamic Characteristics

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION
Input capacitance	C _{iss}		2390.8		pF	V _{GS} =0 V, V _{DS} =50 V, f=100 kHz
Output capacitance	C _{oss}		154.1		pF	
Reverse transfer capacitance	C _{rss}		3.9		pF	
Turn-on delay time	t _{d(on)}		32.4		ns	V _{GS} =10 V, V _{DS} =400 V, R _G =2 Ω, I _D =12.5 A
Rise time	t _r		30.8		ns	
Turn-off delay time	t _{d(off)}		63.2		ns	
Fall time	t _f		4.9		ns	

■ Gate Charge Characteristics

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION
Total gate charge	Q_g		41.9		nC	$I_D=12.5\text{ A}$, $V_{DS}=400\text{ V}$, $V_{GS}=10\text{ V}$
Gate-source charge	Q_{gs}		10.4		nC	
Gate-drain charge	Q_{gd}		14.1		nC	
Gate plateau voltage	$V_{plateau}$		5.7		V	

■ Body Diode Characteristics

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION
Diode forward current	I_S			25	A	$V_{GS} < V_{th}$
Pulsed source current	I_{SP}			75		
Diode forward voltage	V_{SD}			1.4	V	$I_S=25\text{ A}, V_{GS}=0\text{ V}$
Reverse recovery time	t_{rr}		365.2		ns	$V_R=400\text{ V}, I_S=12.5\text{ A}$, $di/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	Q_{rr}		4.7		μC	
Peak reverse recovery current	I_{rrm}		24.9		A	

■ Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ }^{\circ}\text{C}$.
- 5) $V_{DD}=100\text{ V}$, $R_G=25\text{ }\Omega$, $L=80\text{ mH}$, starting $T_j=25\text{ }^{\circ}\text{C}$.

■ Electrical Characteristics Diagrams

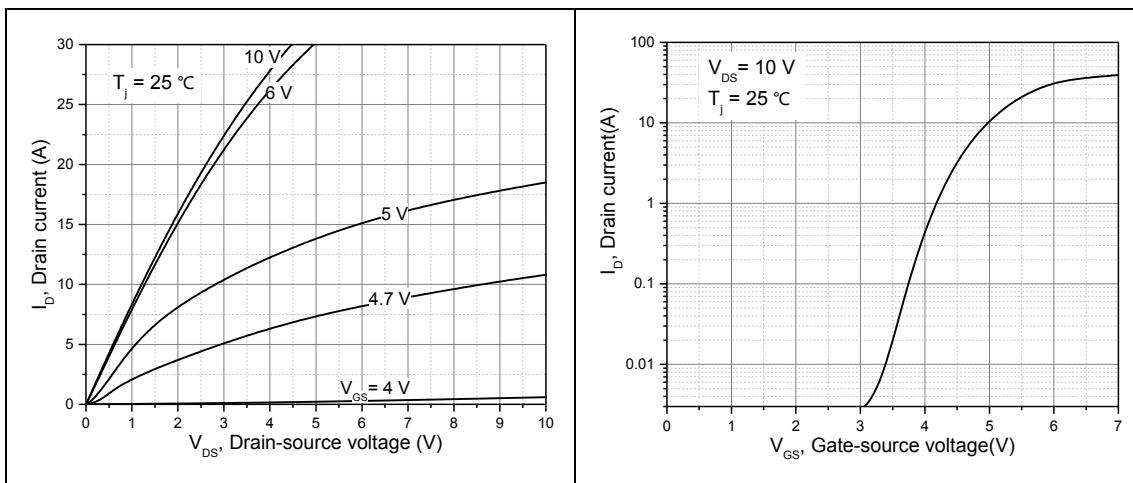


Figure 1, Typ. output characteristics

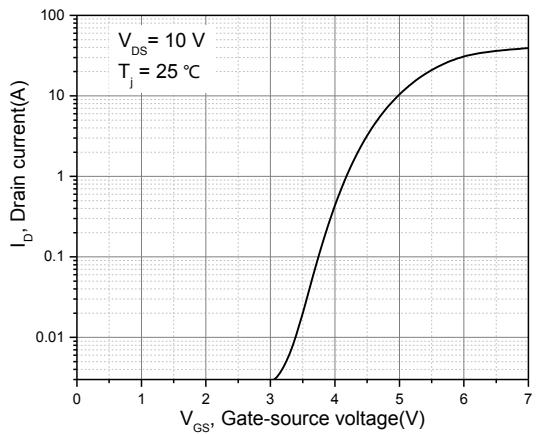


Figure 2, Typ. transfer characteristics

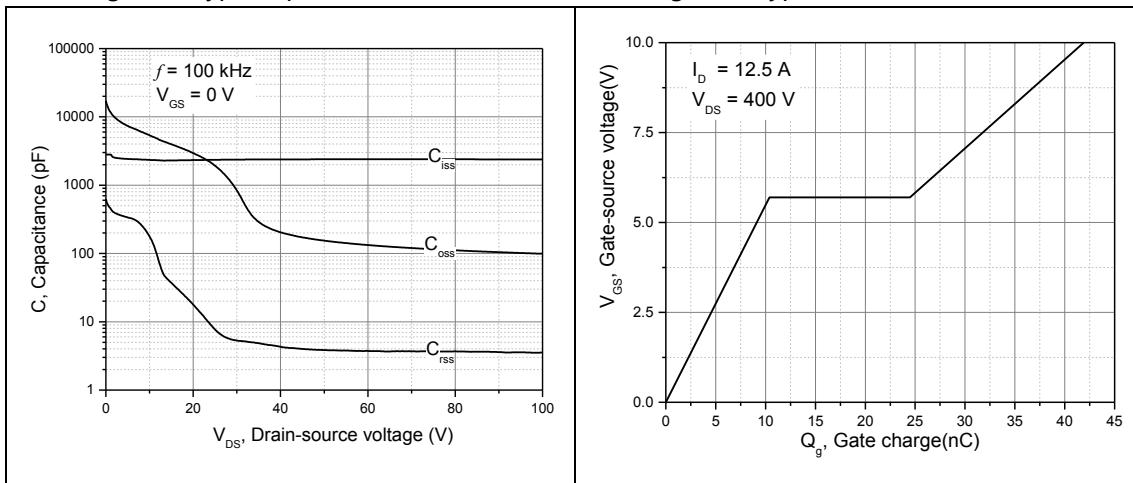


Figure 3, Typ. capacitances

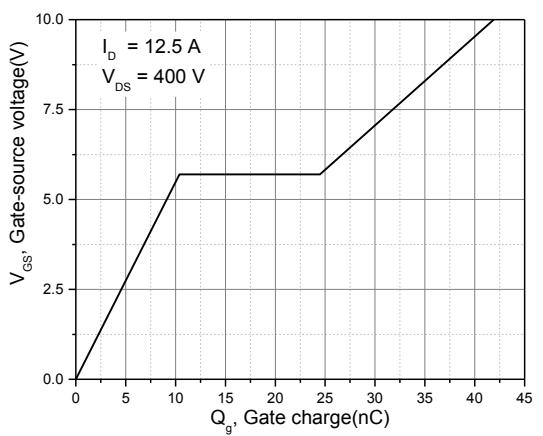


Figure 4, Typ. gate charge

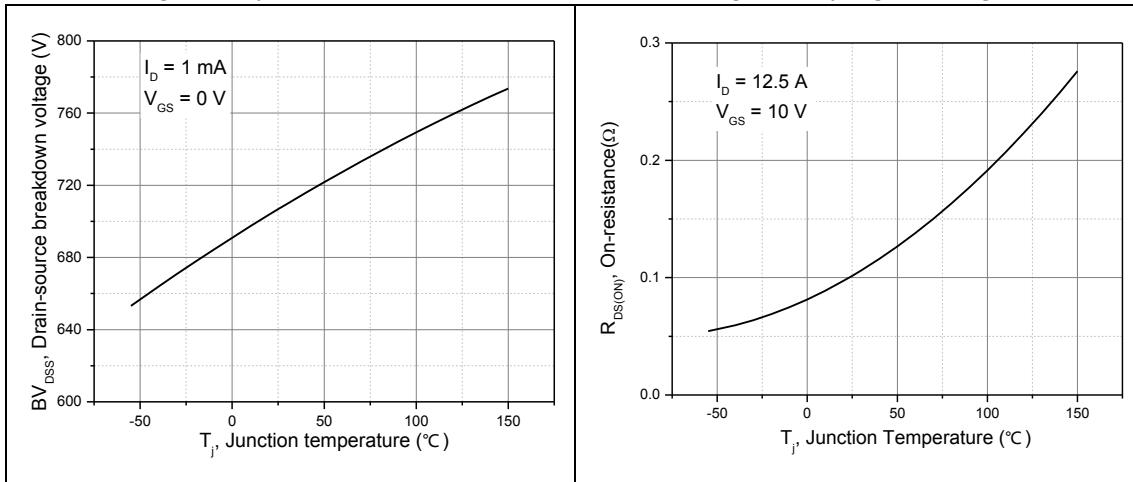


Figure 5, Drain-source breakdown voltage

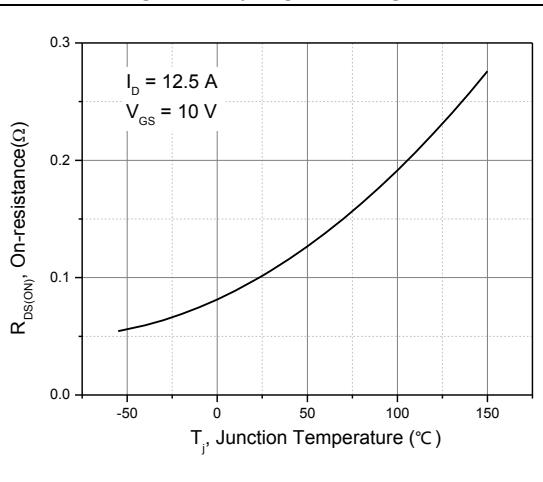


Figure 6, Drain-source on-state resistance

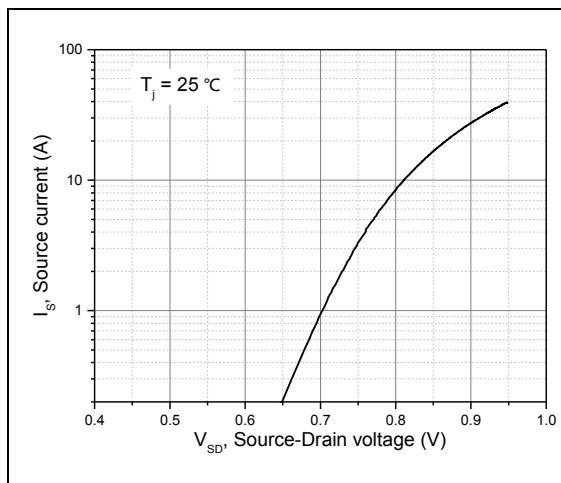


Figure 7, Forward characteristic of body diode

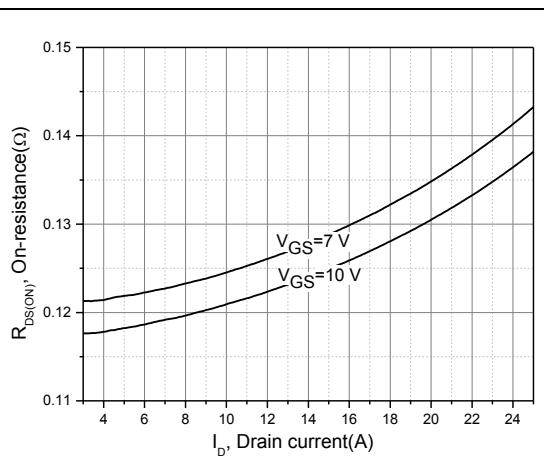


Figure 8, Drain-source on-state resistance

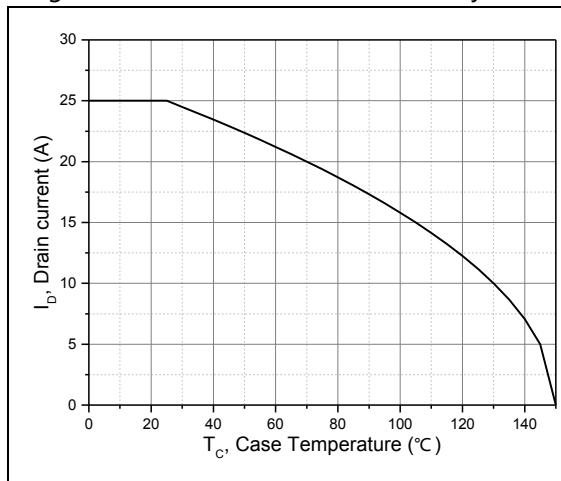
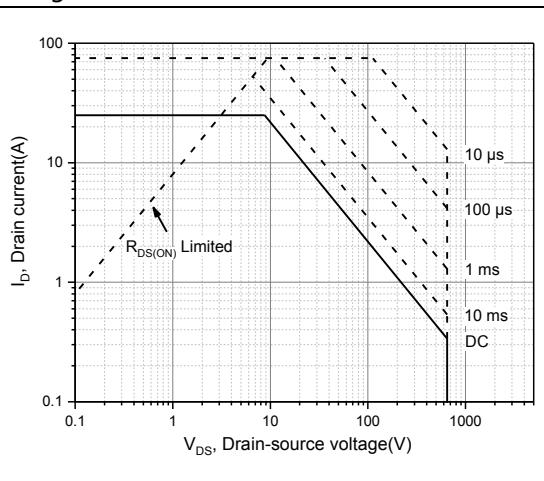
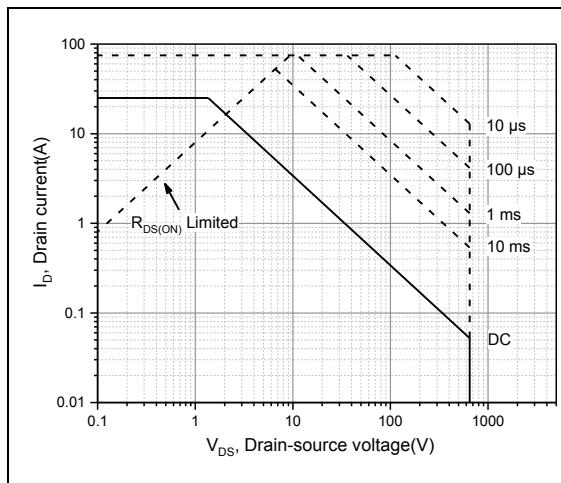


Figure 9, Drain current


 Figure 10, Safe operation area for
TO247/TO263 $T_C=25^\circ\text{C}$

 Figure 11, Safe operation area for TO220F
 $T_C=25^\circ\text{C}$

■ Test circuits and waveforms

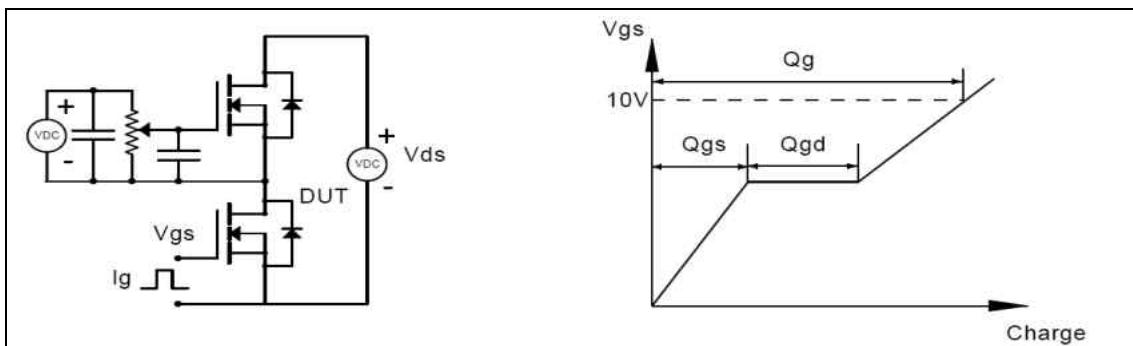


Figure 1, Gate charge test circuit & waveform

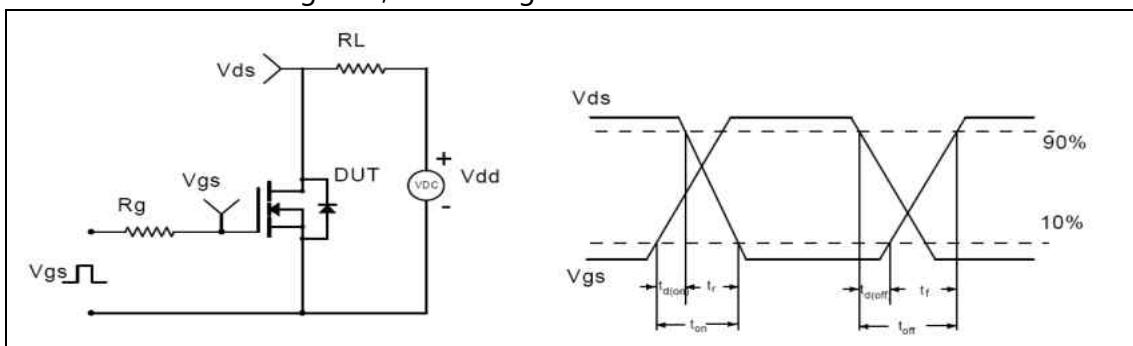


Figure 2, Switching time test circuit & waveforms

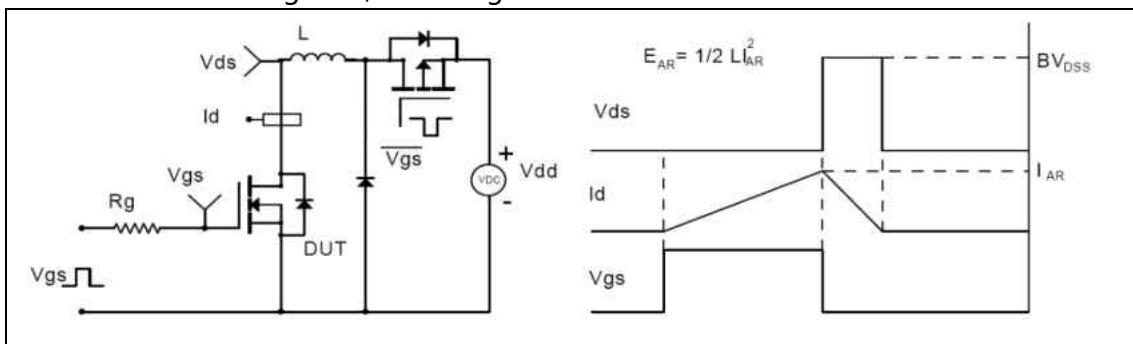


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

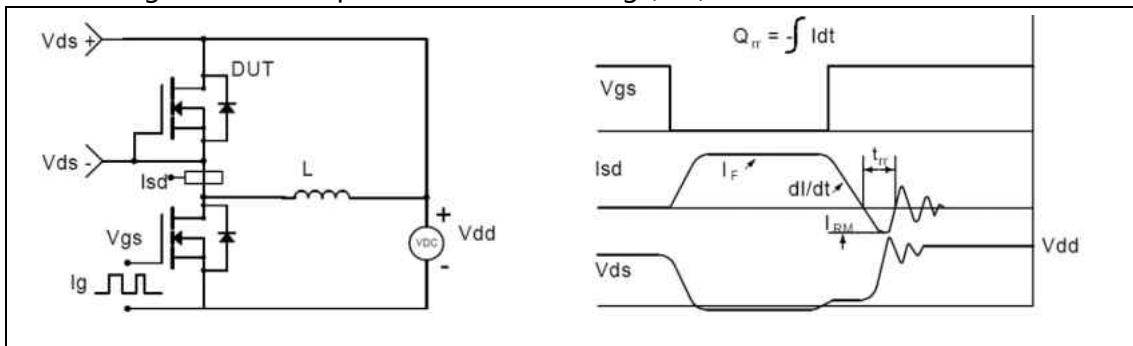
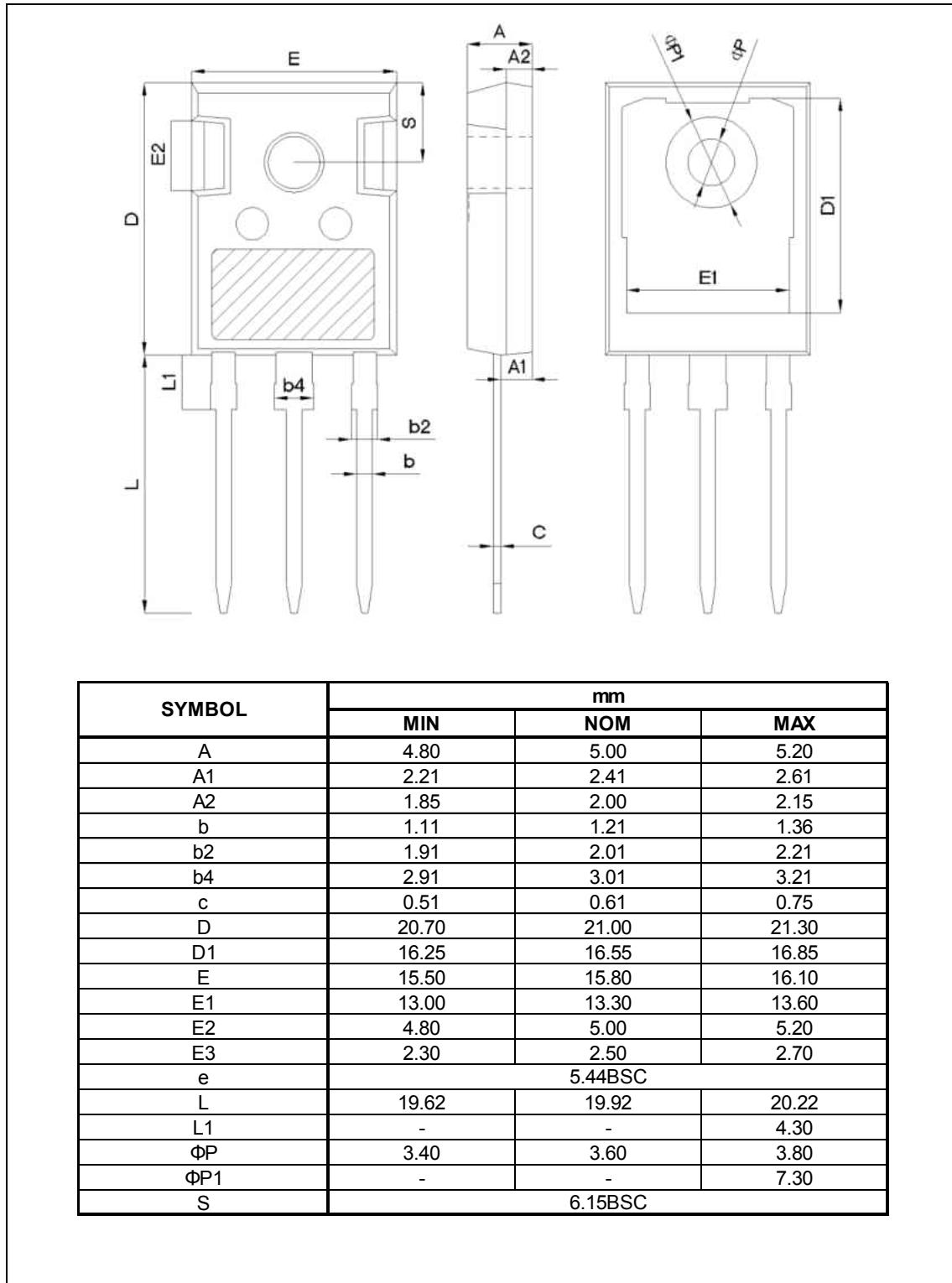


Figure 4, Diode reverse recovery test circuit & waveforms

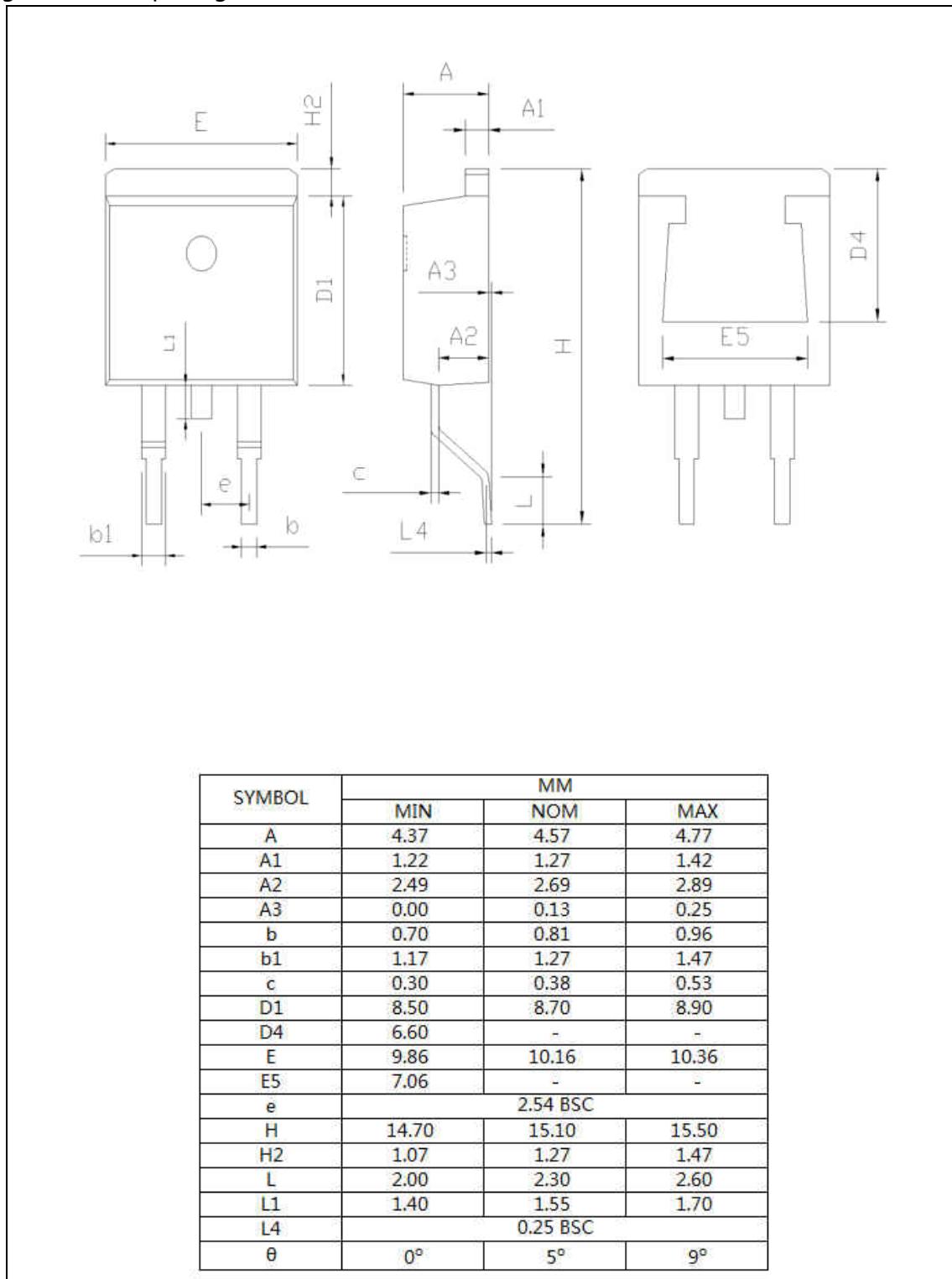
■ Package Information

Figure1, TO247 package outline dimension



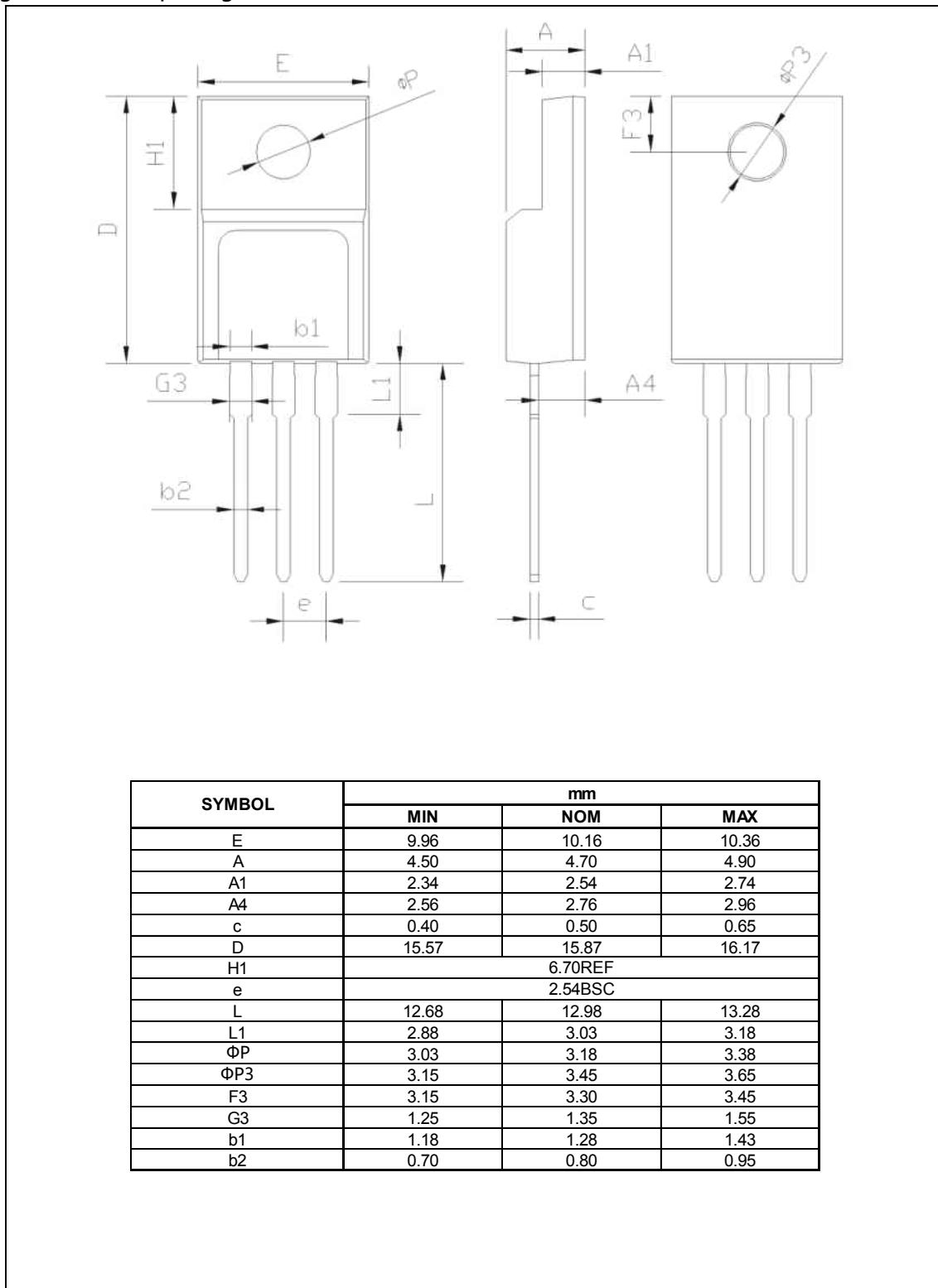
■ Package Information

Figure2, TO263 package outline dimension



■ Package Information

Figure3, TO220F package outline dimension



■ Ordering Information

Package	Units/Tube	Tapes/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO247	30	11	330	6	1980
TO263Option1	50	20	1000	6	6000
TO220F	50	20	1000	6	6000

Package	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO263Option2	800	1	800	5	4000

■ Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG65R125HF	TO247	yes	yes	yes
OSG65R125KF	TO263	yes	yes	yes
OSG65R125FF	TO220F	yes	yes	yes